



Embedded Systems Week

www.esweek.org

October 11-16, 2020
Shanghai, China



Call for Papers, Workshops, Tutorials, Special Sessions

• CASES • CODES+ISSS • EMSOFT • Trustworthy IoT Day • NOCS • Workshops • Tutorials •

About Embedded Systems Week (ESWEEK)

Embedded Systems Week (ESWEEK) is the premier event covering all aspects of hardware and software design for smart, intelligent and connected computing systems. By bringing together three leading conferences (CASES, CODES+ISSS, EMSOFT), one symposium (NOCS), and several workshops and tutorials, ESWEEK allows attendees to benefit from a wide range of topics covering the state of the art in embedded systems research and development.

One Registration, three Conferences!

Registered attendees can attend sessions in any of the ESWEEK conferences (CASES, CODES+ISSS, EMSOFT). Please note that tutorials, NOC symposium, and workshops may require separate registration.

Journal Track:

Abstract Submission: April 3, 2020
Full Paper Submission: April 10, 2020 (firm)
Notification of Acceptance: July 6, 2020

Work-in-Progress Track:

Paper Submission: June 5, 2020 (firm)
Notification of Acceptance: July 6, 2020

Workshop Proposals: April 17, 2020

Tutorial Proposals: May 1, 2020

Special Session Proposals: May 1, 2020

CASES

International Conference on
Compilers, Architectures, and
Synthesis for Embedded Systems

CASES is a premier forum where researchers, developers and practitioners exchange information on the latest advances in compilers and architectures for high-performance, low-power embedded systems. The conference has a long tradition of showcasing leading edge research in embedded processor, memory, interconnect, storage architectures and related compiler techniques targeting performance, power, predictability, security, reliability issues for both traditional and emerging application domains. In addition, we invite innovative papers that address design, synthesis, and optimization challenges in heterogeneous and accelerator-rich architectures.

International Conference on
Hardware/Software Codesign
and System Synthesis



The International Conference on Hardware/Software Codesign and System Synthesis is the premier event in system-level design, modeling, analysis, and implementation of modern embedded and cyber-physical systems, from system-level specification and optimization down to system synthesis of multi-processor hardware/software implementations. The conference is a forum bringing together academic research and industrial practice for all aspects related to system-level and hardware/software co-design.

NOCS Symposium

Tutorials

Workshops

EMSOFT

International Conference
on Embedded Software

The ACM SIGBED International Conference on Embedded Software (EMSOFT) brings together researchers and developers from academia, industry, and government to advance the science, engineering, and technology of embedded software development. Since 2001, EMSOFT has been the premier venue for cutting-edge research in the design and analysis of software that interacts with physical processes, with a long-standing tradition for results on cyber-physical systems, which compose computation, networking, and physical dynamics.

Keynotes

Special Day on Trustworthy
Internet-of-Things

Trustworthy
IoT

The Internet of Things (IoT) promises to revolutionize the world by merging network technologies with embedded devices leading to the Internet of physical things. Trust, security, and privacy are central to the achievement of the IoT vision: advanced computation, communication, and storage must be delivered in a safe, secure, and reliable manner. Trustworthy IoT special day will provide a forum for academia and industry to present and discuss innovative ideas and solutions related to all facets of trustworthy internet-of-things. Submissions to the Trustworthy IoT day are via the three conferences.

Journal-integrated Publication Model: All full papers accepted for the three conferences will be published in the IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)

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Paper Process

ESWEEK 2020 continues a dual publication model comprising the Journal track and the Work-in-Progress (WiP) track. Journal track papers, which are full-length papers describing mature work, will be published in the IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD). The WiP track papers, which are short (2-page) papers representing not-yet-mature but promising research, will be published in the ESWEEK proceedings and will be listed as regular publications within the IEEE and/or ACM digital libraries. Authors of WiP papers have the opportunity to publish the extended form of their work in any conference or journal they prefer. Journal and WiP papers are mutually exclusive, i.e., a work can only be in submission in one of the two tracks. For more information on the publishing process, refer to <http://www.esweek.org/author-information>.

Workshops, Tutorials, Special Sessions

Call for Workshop Proposals

ESWEEK 2020 will host several workshops on Oct. 15/16. ESWEEK workshops are excellent opportunities to bring together researchers and practitioners from different communities to share their experiences in an interactive atmosphere. We invite you to submit workshop proposals on any topic related to the broad set of research, education, and application areas in embedded systems before **April 17, 2020**.

Call for Tutorial Proposals

ESWEEK 2020 is looking for high-quality tutorials that will take place on Oct. 11. Tutorials offer a unique opportunity where presenters can interact with attendees and attendees can gain in-depth knowledge on specific topics. Tutorials on all topics related to embedded system design, analysis and development are welcome and can be either half or full day, lecture style or hands on. We invite you to submit tutorial proposals before **May 1, 2020**.

Call for Special Session Proposals

ESWEEK 2020 will host several special sessions. They should cover hot, contemporary topics that are complementary to regular sessions and can constitute individual presentations, panels or other formats. Participants of each accepted special session will have the opportunity to co-author an overview paper (maximum 10 pages) of the session, published in the ESWEEK proceedings. We invite you to submit special session proposals on any topic related to the broad areas of interest of the conference or beyond before **May 1, 2020**.

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- Andreas Gerstlauer, University of Texas Austin, US
- Petru Eles, Linköping University, SE

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- Umit Ogras, Arizona State University, US

CODES+ISSS

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